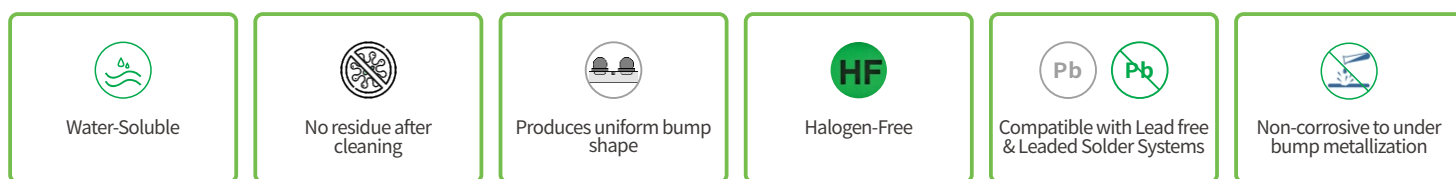


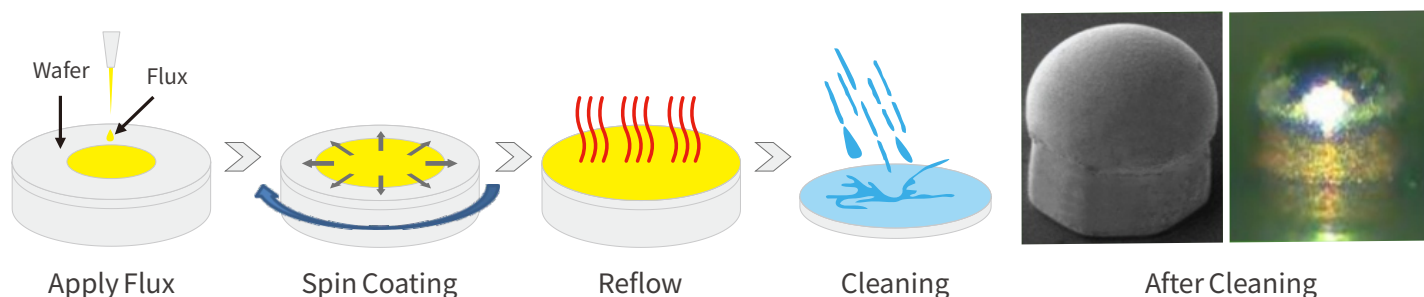
# WF-710/711 WAFER FLUX FOR BUMPING

Qualitek has developed a Water-Soluble flux system designed to remove surface oxides from solder bumps on wafers. WF-series produces hemispherical bumps without inducing solder bridging nor solder removal. WF-series is designed for both spin-coat and spray applications.

## Main Features



## Application



## Typical Analysis

PROPERTIES	SPECIFICATIONS		METHOD
	WF-710	WF-711	
Flux Classification	ORL0	ORH0	IPC-J-STD-004B
Appearance	Amber to Brown	Amber to Brown	Visual
pH - 5% Aqueous Solution	4.2 - 5.2	2.5 - 6.5	QIT
Halide Content	Halide - Free	Halide - Free	IPC-TM-650 2.3.33 (Silver Chromate Test)
Halogen Content	Halogen - Free	Halogen - Free	EN 14582
Brookfield Viscosity (@10rpm)	100 - 300 cps	100 - 300 cps	IPC-TM-650 2.4.34 (Modified)
Specific Gravity (25±0.5°C)	1.000 - 1.100	1.030 - 1.070	QIT
Surface Insulation Resistance (Cleaned)	>1.0 x 10 <sup>9</sup> ohms	>1.0 x 10 <sup>9</sup> ohms	IPC-TM-650 2.6.3.3



LEARN MORE: [www.qualitek.com](http://www.qualitek.com)  
 CHINA: +86-755-28522814  
 SINGAPORE: +65-67957757

USA: +1-630-6288083  
 EUROPE: +44-151-3340888  
 PHILIPPINES: +63-47-9354119

